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Electrodeposition of high permeability films

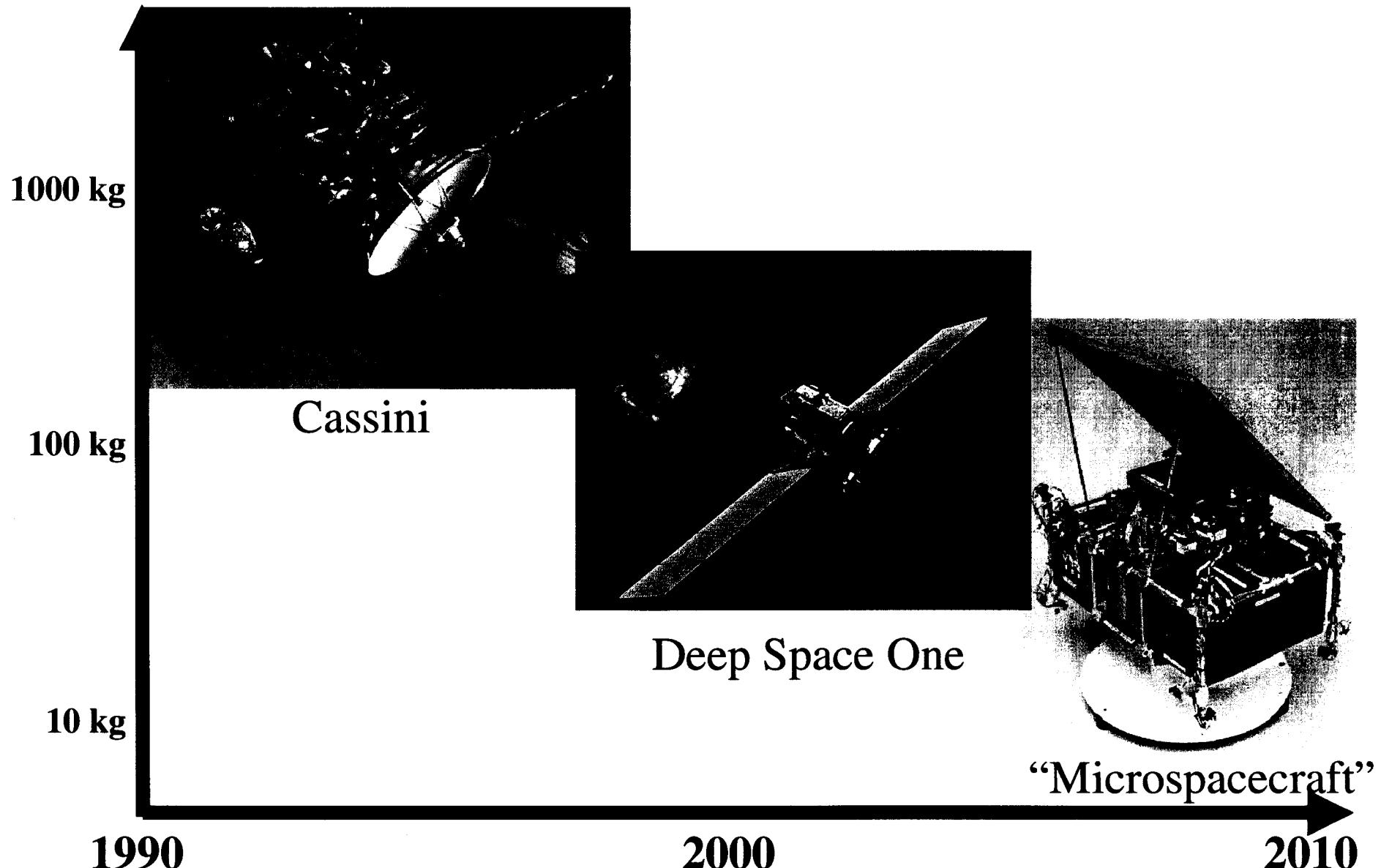
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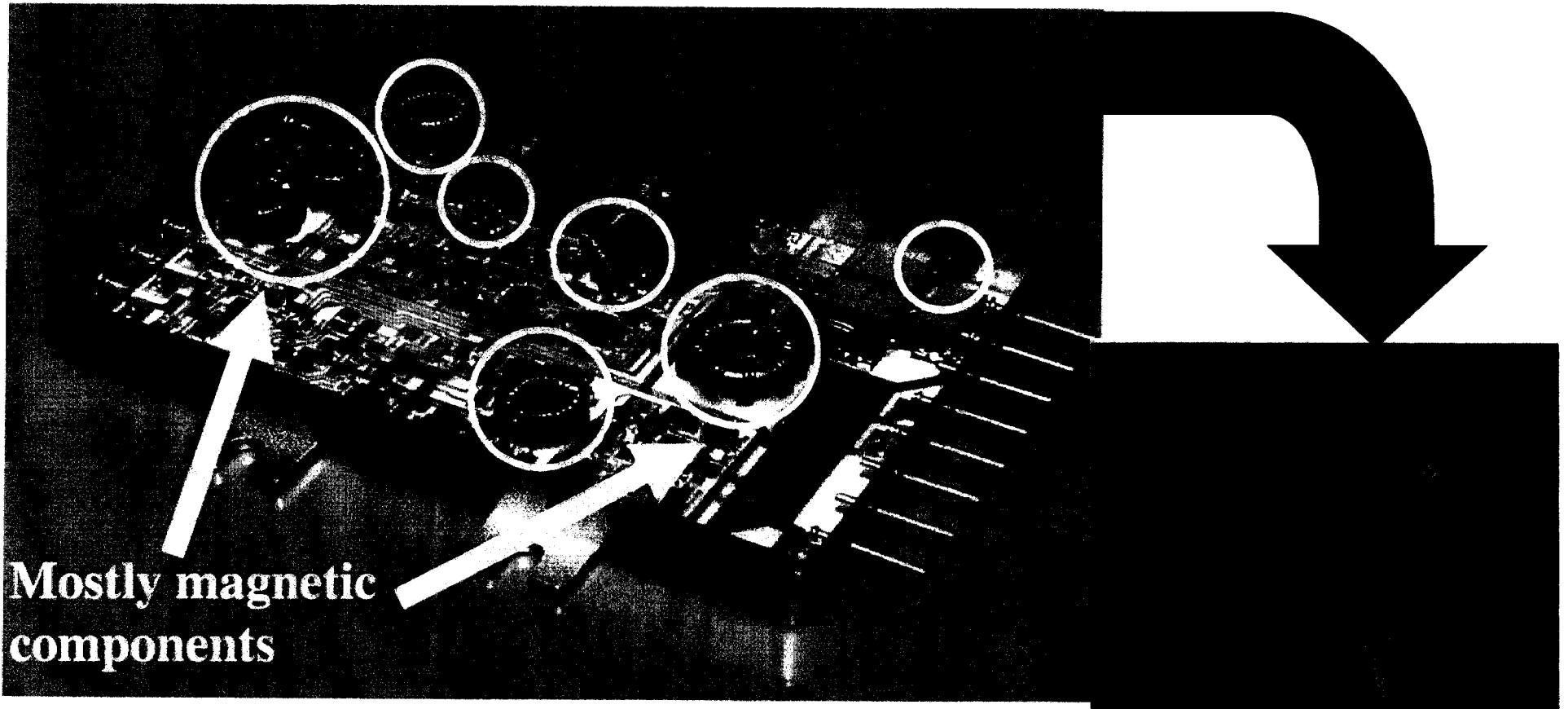


Reduction in spacecraft mass and volume





Power electronics continue to defy miniaturization **JPL**



Mostly magnetic
components

State-of-the-art, space rated dc-dc converter
 $4000 \text{ mm}^2, 80 \text{ g}$

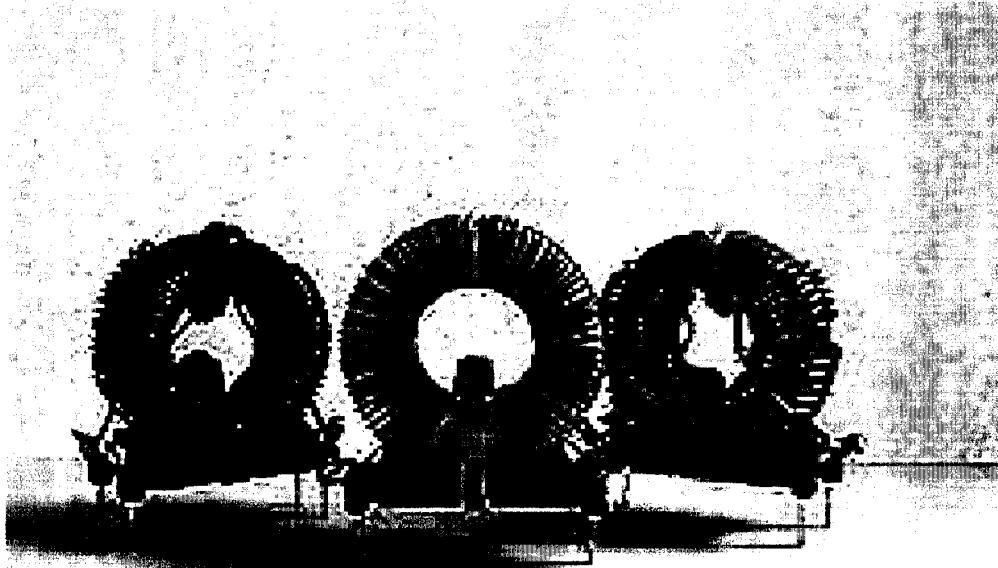
Problem: How do we integrate “passive” components?

**Integrated, on-chip
power converter**
 $4 \text{ mm}^2, 1 \text{ g}$



Discrete vs. integrated inductors

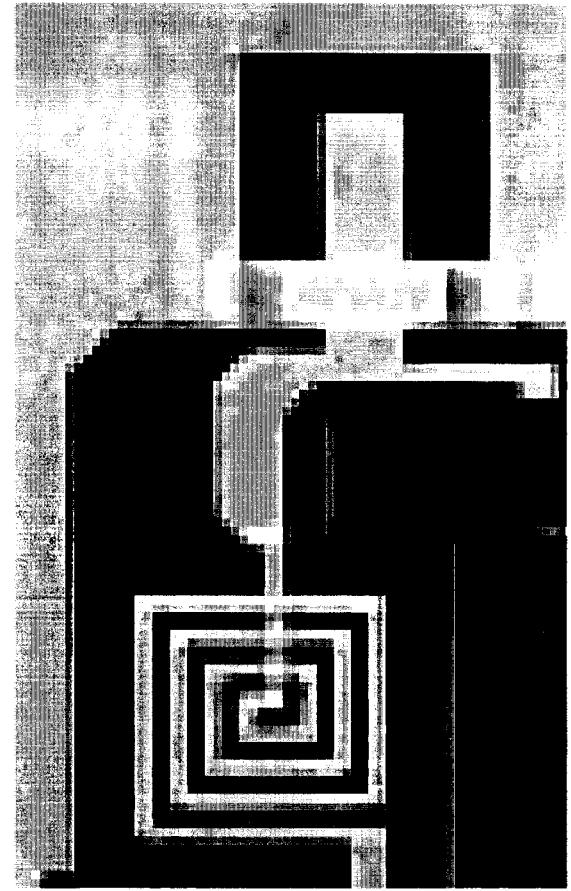
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Discrete, surface mount inductors

Heavy gauge copper wire wound around
a ferrite based core

High inductance *but*
high mass and volume



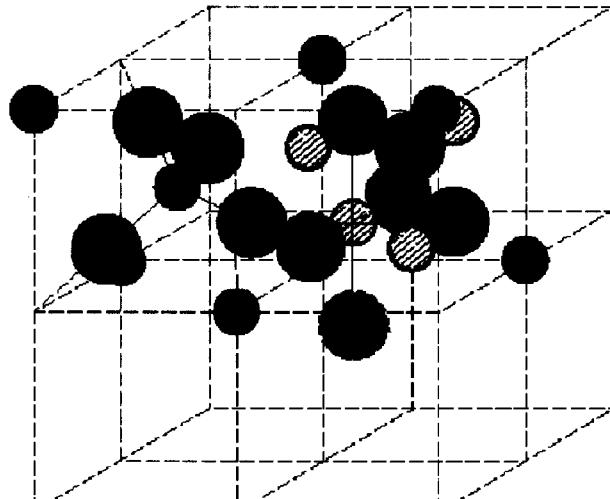
Integrated inductors

Spiral metal trace on silicon
Low mass and volume *but*
low inductance



Classic power magnetics are incompatible with silicon based technology

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Ferrite Spinel Structure

Ferrites or “Ceramic Magnets”

- *classic high frequency material* used for power
- difficult to deposit, require high T processing

Metallic Alloys

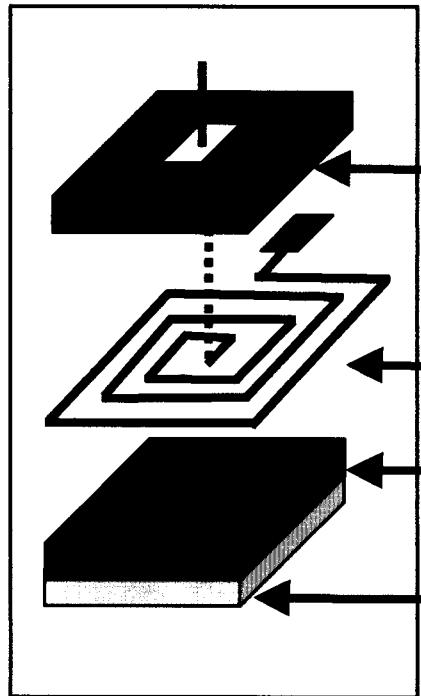
- well suited for thick/thin film deposition
- *low temperature*, silicon compatible processing
- *low resistivity* limits high frequency application

Typical Magnetic Properties	B _{max} , G	μ	H _c , Oe	ρ , $\mu\Omega\text{-cm}$	Fabrication Methods
Ferrites	5,000	30	100	10 ⁷	Ceramic methods
Metallic Alloys	20,000	1000	<0.1	5 to 50	sputtering, electroplating



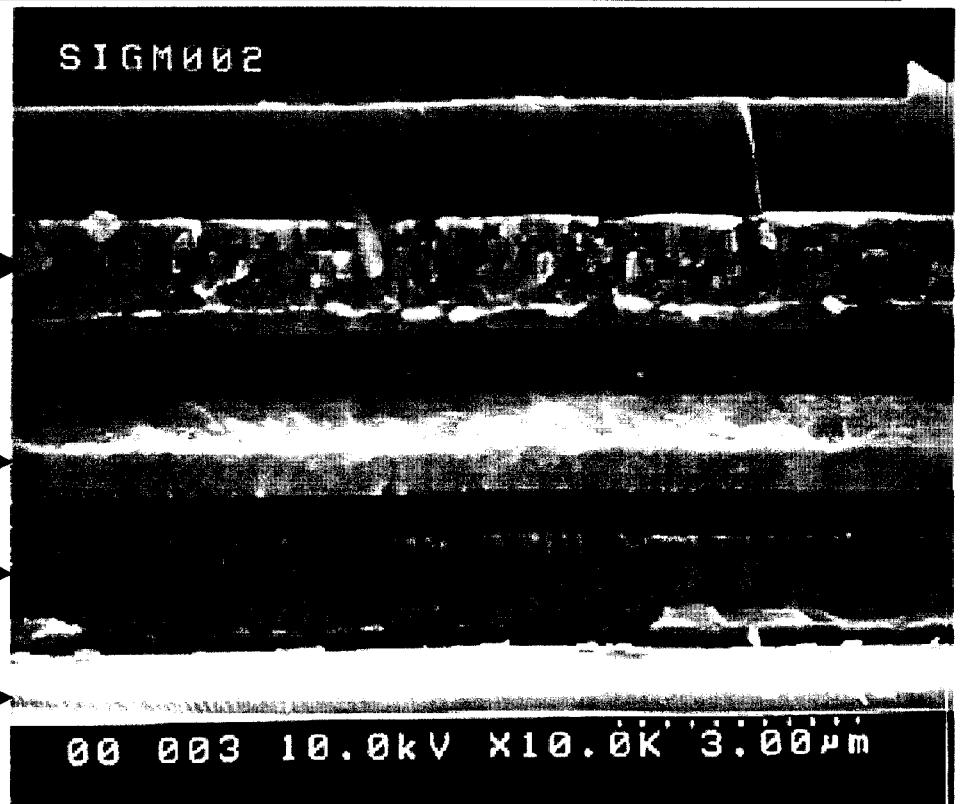
A magnetic “microinductor” on a silicon wafer

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6 mm²

$$L \propto N^2, A, \mu$$



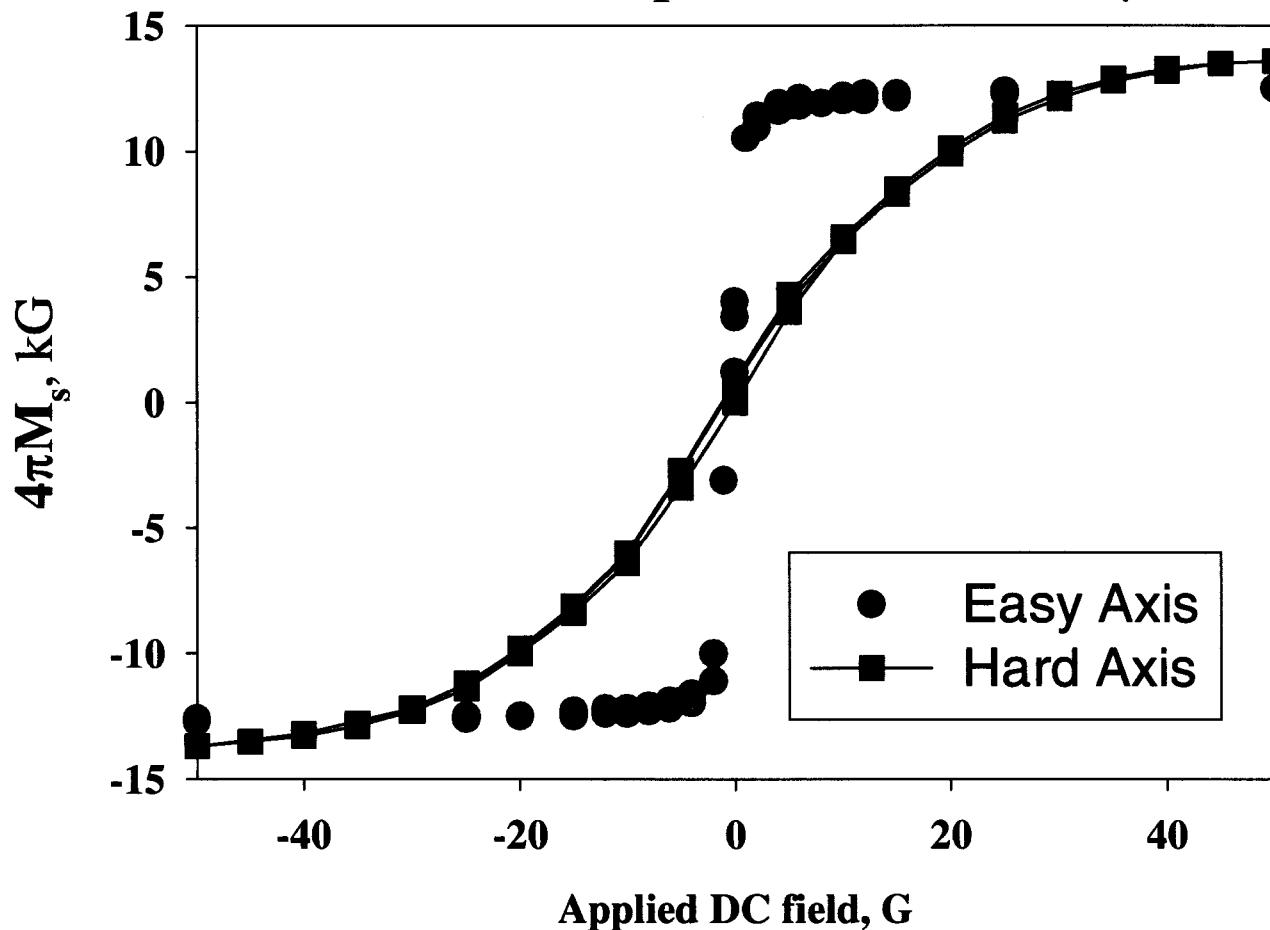
SEM Cross section of a
“micro-inductor” with magnetic
thin films (1 μm)



rf sputtered $\text{Co}_{90}\text{Zr}_{10}$ films display excellent soft magnetic properties



- low coercivity
- high saturation magnetization
- difficult to deposit films over 1 μm

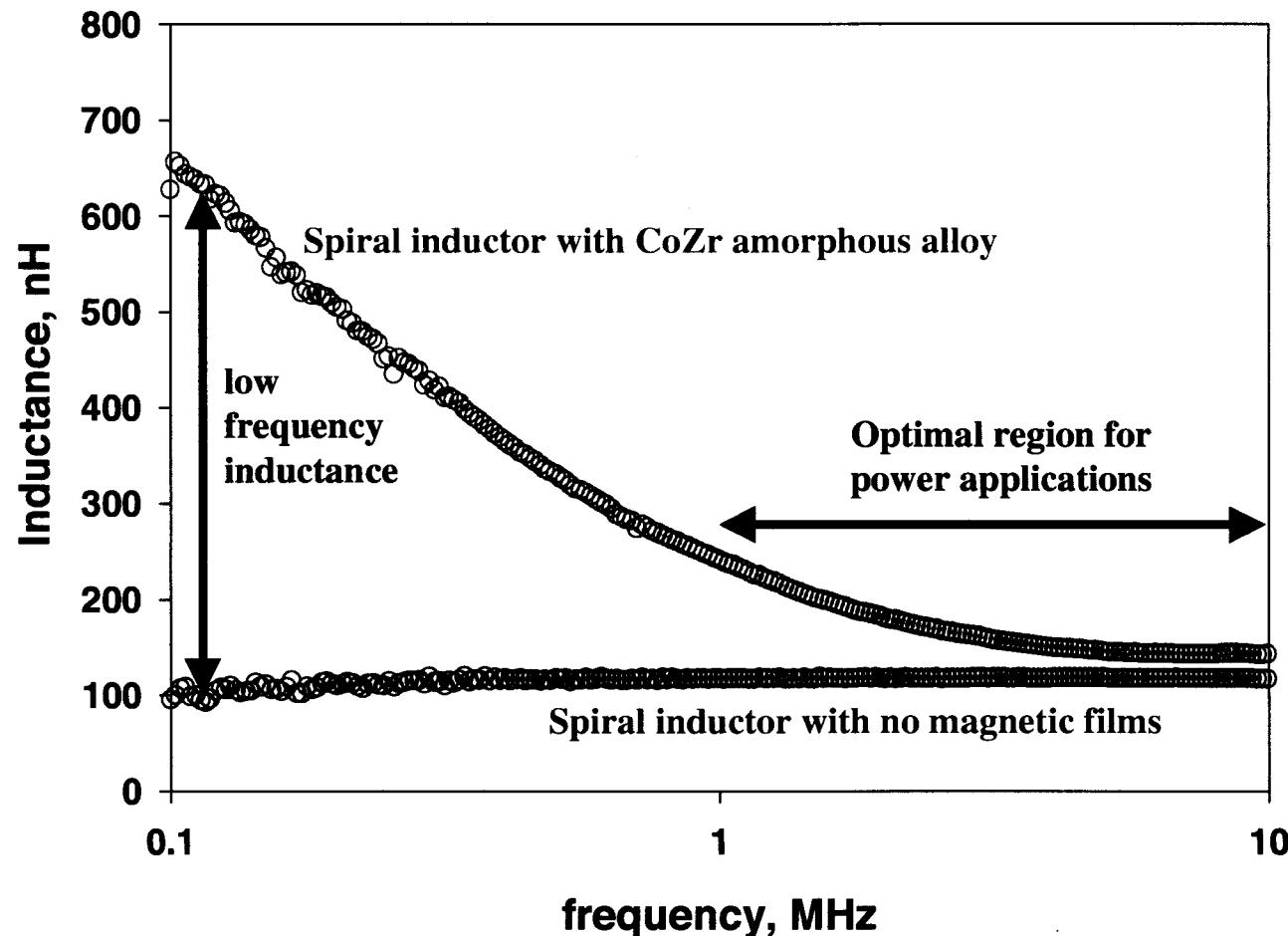




Spiral microinductors with $\text{Co}_{90}\text{Zr}_{10}$ magnetic layers

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eddy currents in the magnetic material
degrade inductance at high frequencies





Eddy currents and skin depth



“Skin Depth”

$$\delta \propto \left(\frac{\rho}{f\mu} \right)^{-1/2}$$

Reduces effective
area of magnetic
material

Magnetic
film
thickness

Unused material

← Metal spiral
carrying ac current

Eddy currents
set up flux in
the *opposite*
direction



Alternative Magnetic Materials



Skin depth and eddy currents are dictated by the resistivity

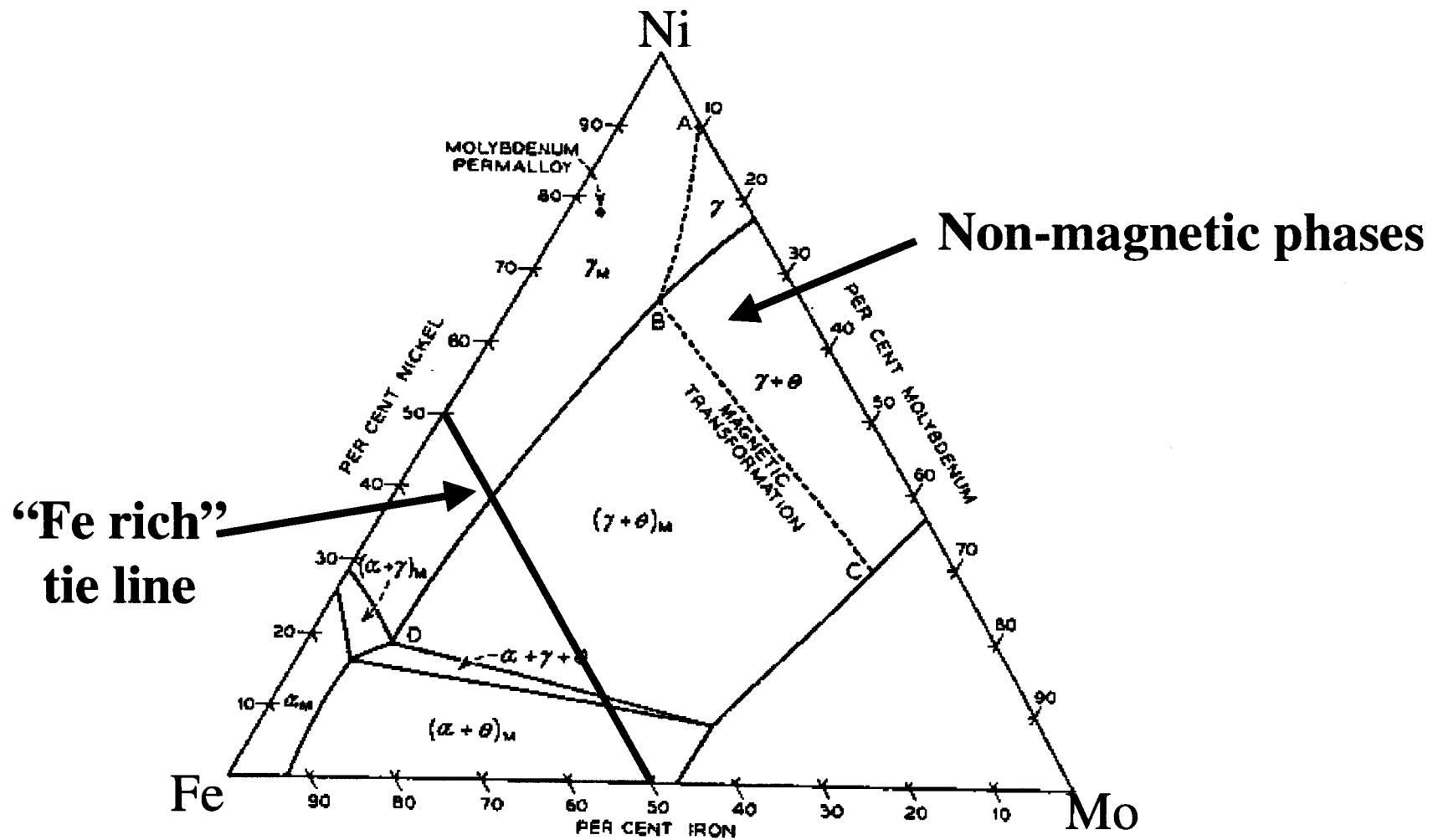
	Permeability	H_c Oe	$4\pi M_s$ Oe	Resistivity, $\mu\Omega\text{-cm}$
Permalloy (80 Ni, 20 Fe)	8,000	0.05	10,800	16
45 Ni, 55 Fe	2,500	0.3	16,000	45
4 Mo, 79 Ni, 17 Fe	20,000	0.05	8,700	55
3 Mo, 47 Ni, 50 Fe	2,000	0.1	14,500	80

*Values based on bulk material



Ni-Fe-Mo phase diagram

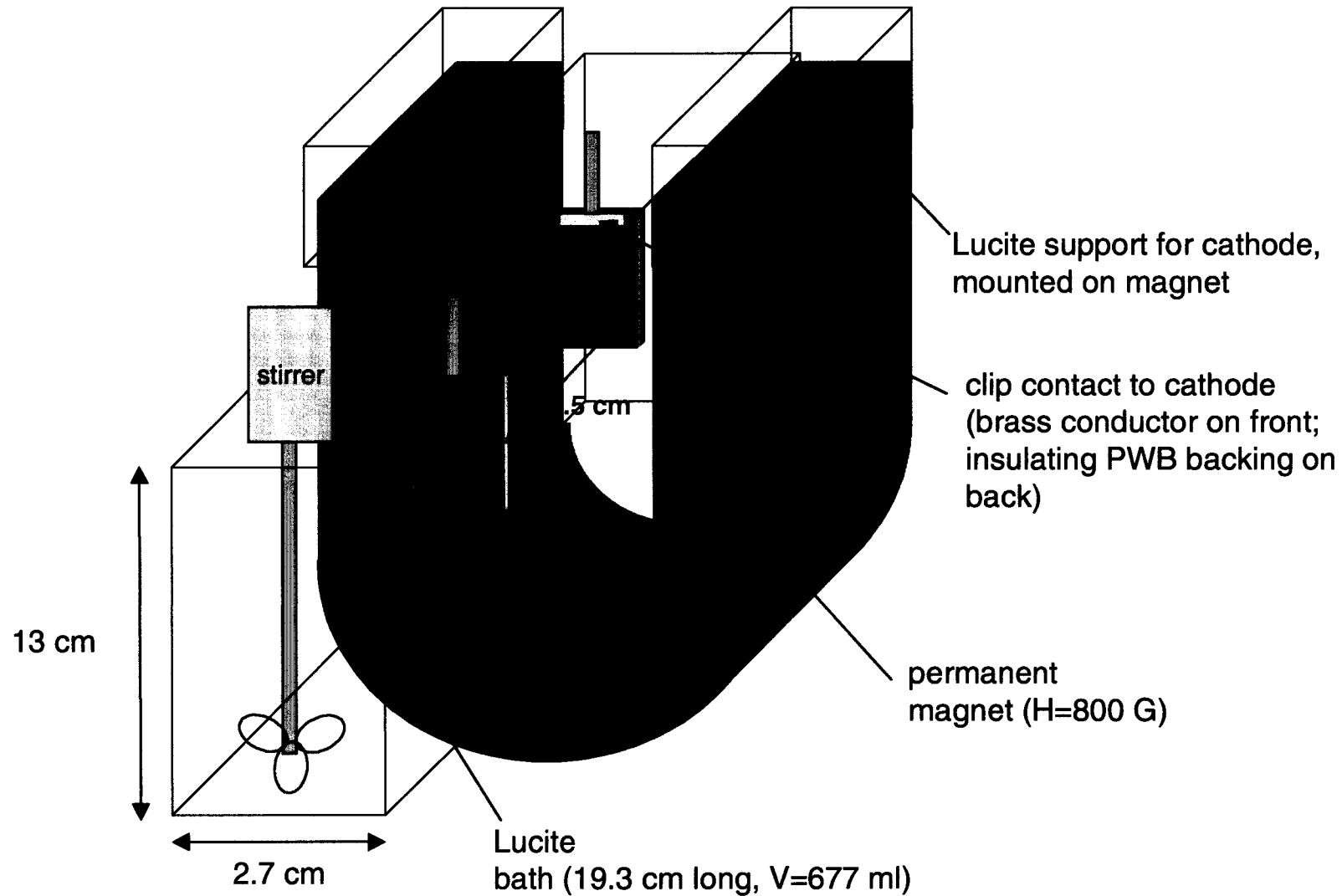
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Electrodeposition Bath

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Typical Electroplating Bath



NiSO₄•6H₂O

60 g/L

FeSO₄•7H₂O

3-15 g/L

Na₂MoO₄

0.2-1 g/L

ammonium chloride

20 g/L

citric acid monohydrate

60 g/L

sodium saccharin dihydrate

1.5 g/L

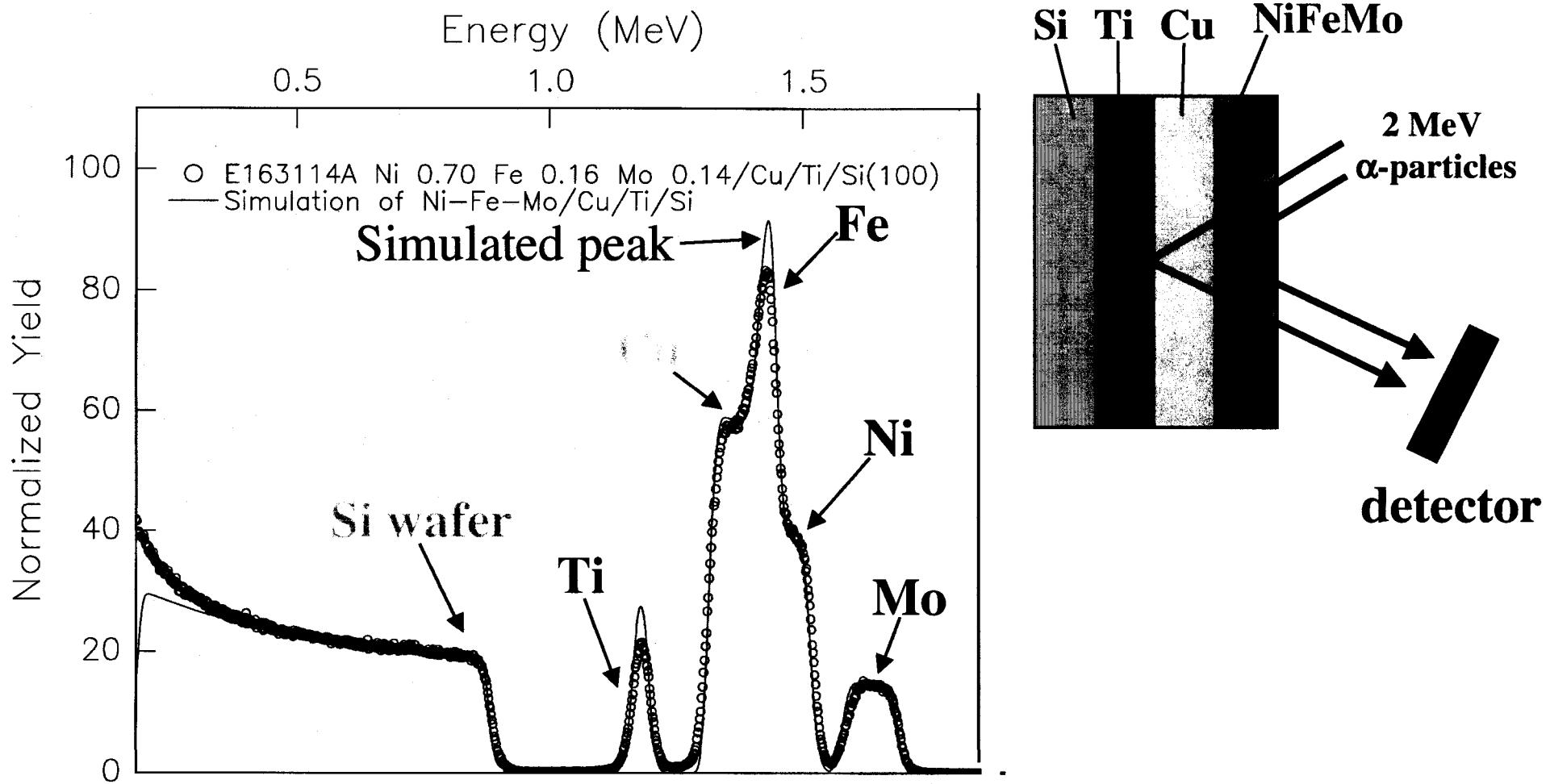
sodium dodecyl sulfate

0.1 g/L



Rutherford Backscattering Spectrometry

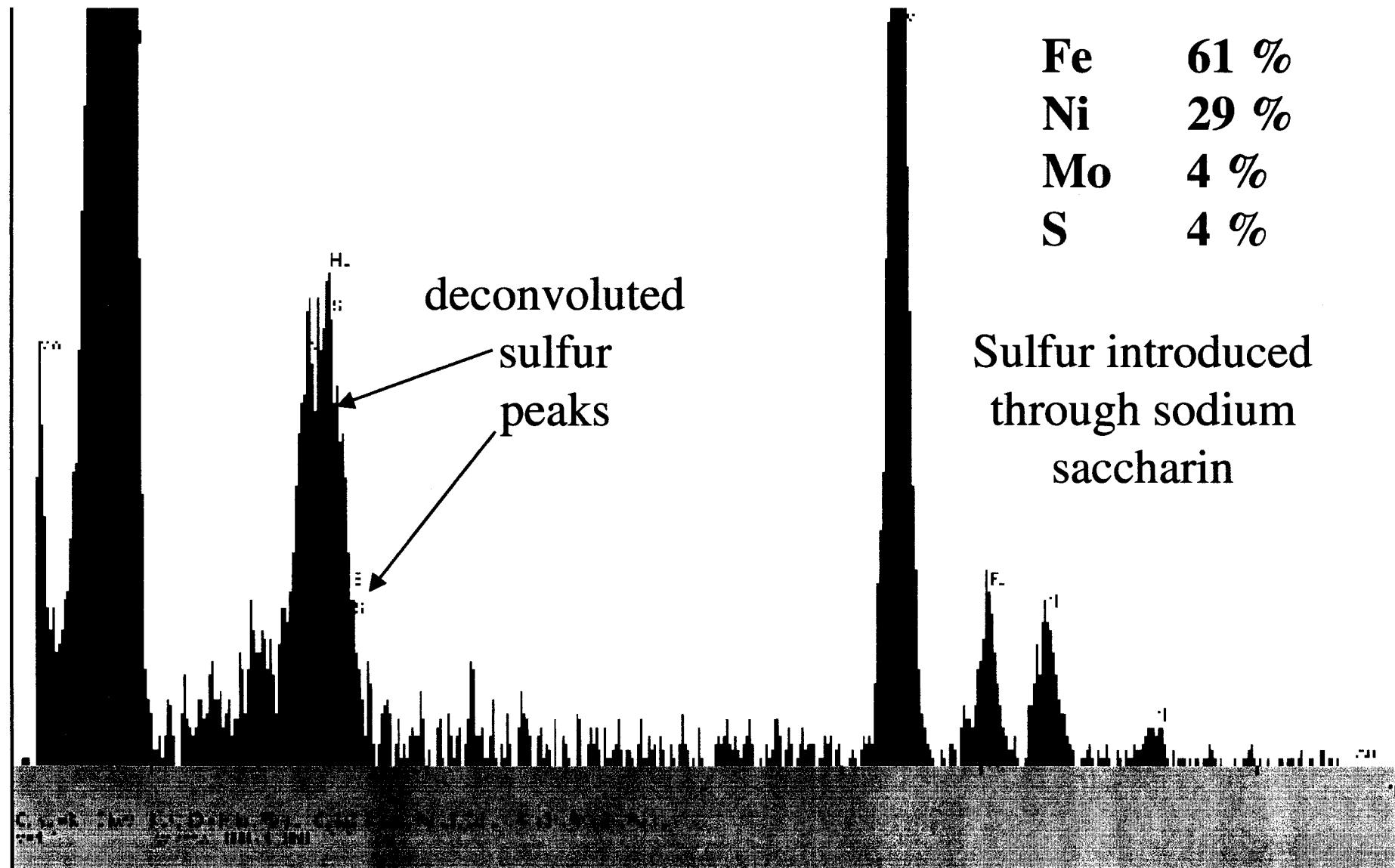
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Compositional Analysis by EDS

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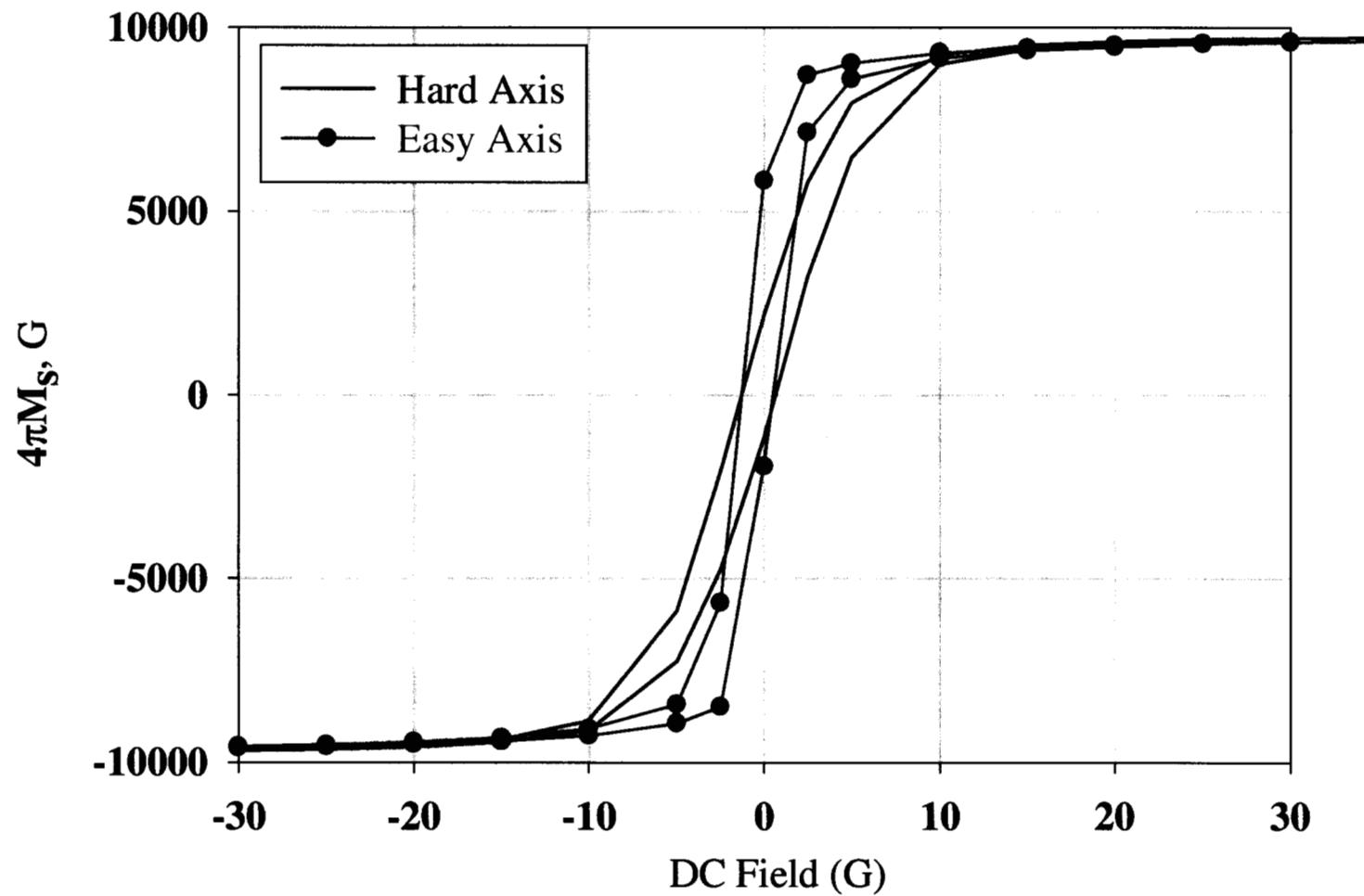




Electroplated Ni-Fe-Mo films

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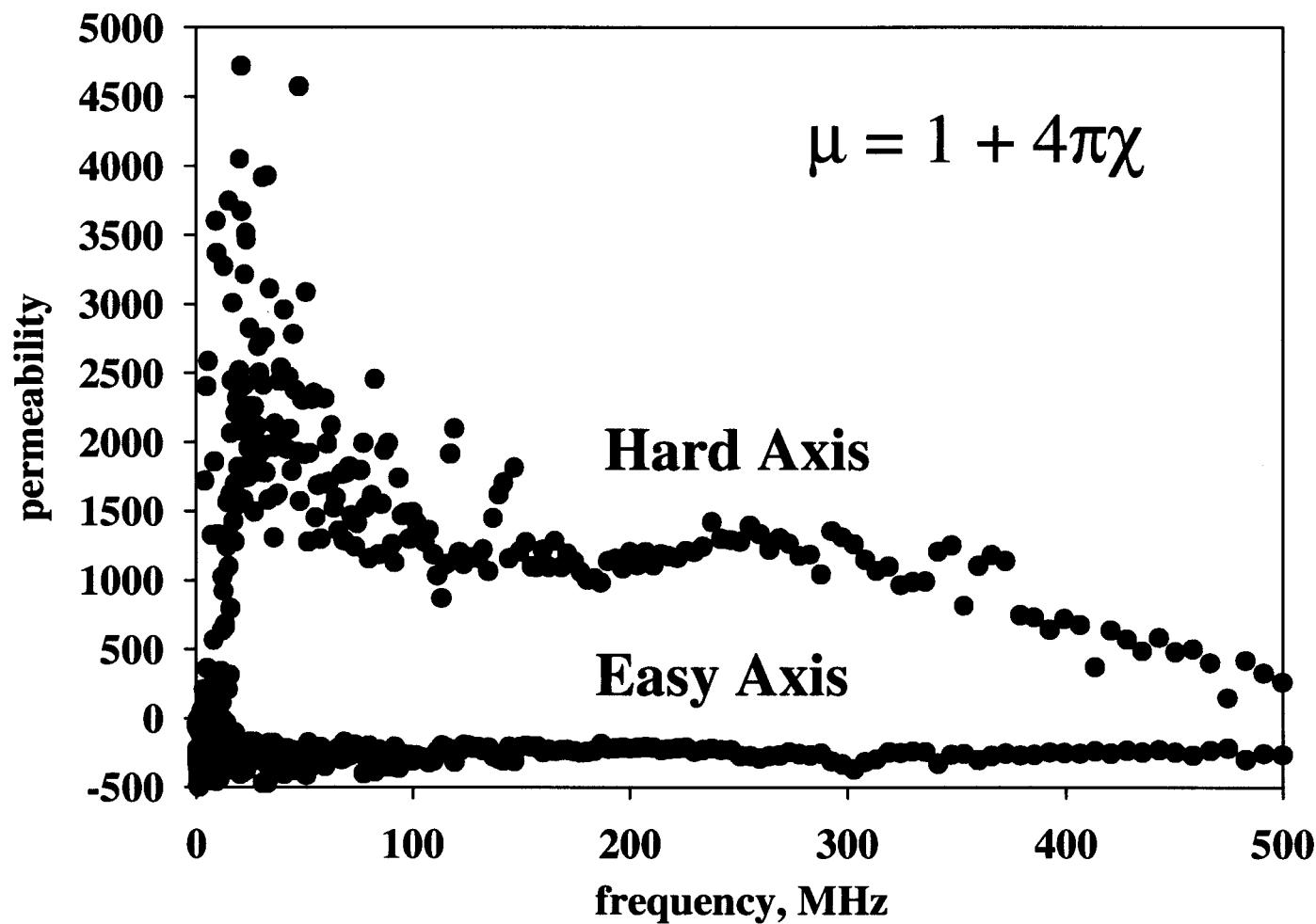
- Anisotropy introduced by plating in a field
- Excellent soft magnetic properties





Hard and Easy Axis Permeability

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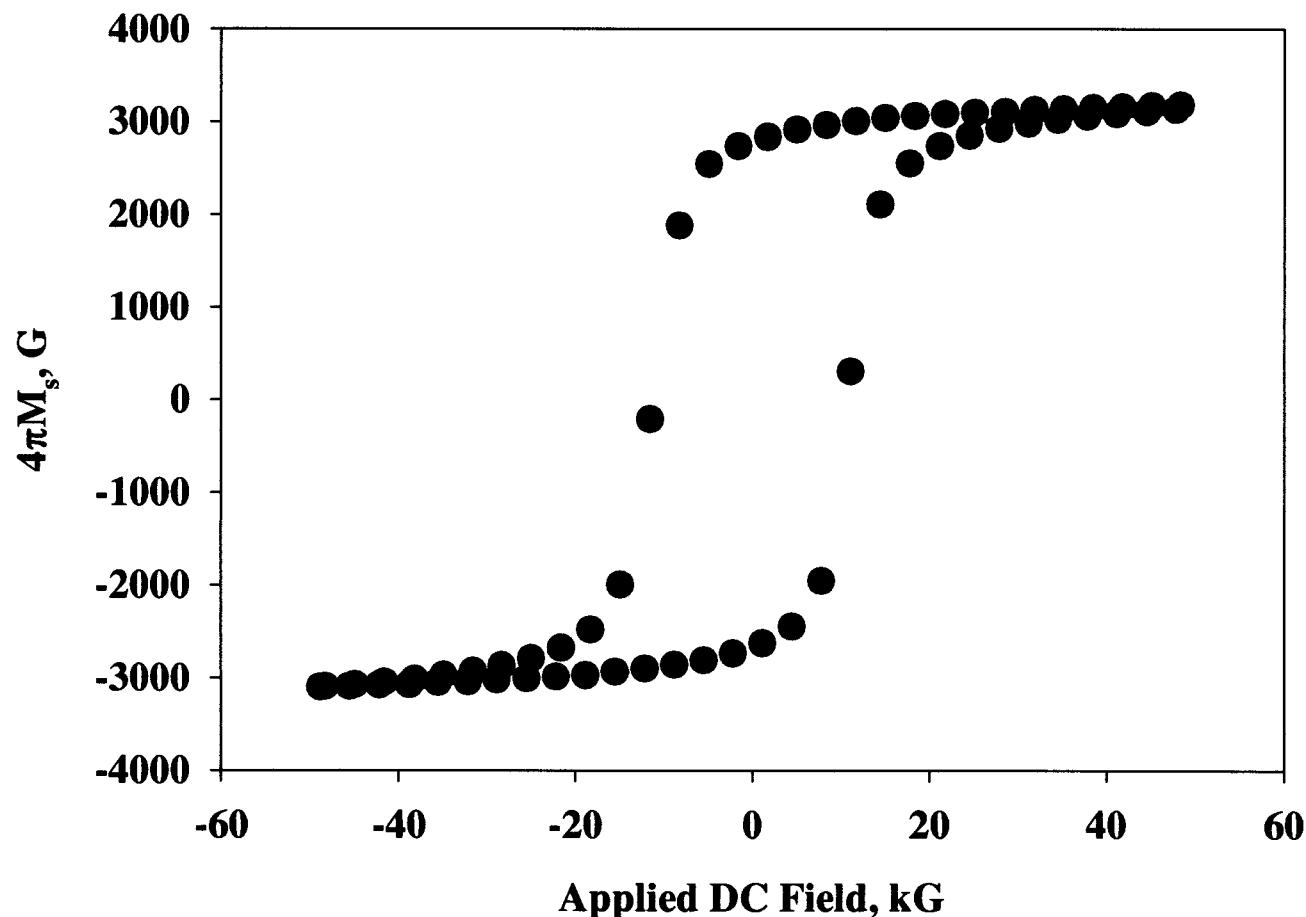




Influence of bath composition on magnetic properties

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Films deposited with high Fe^{+2} and Mo^{+6} concentration often
result in films with poor magnetic properties





Molybdate Equilibria in Acidic Solution

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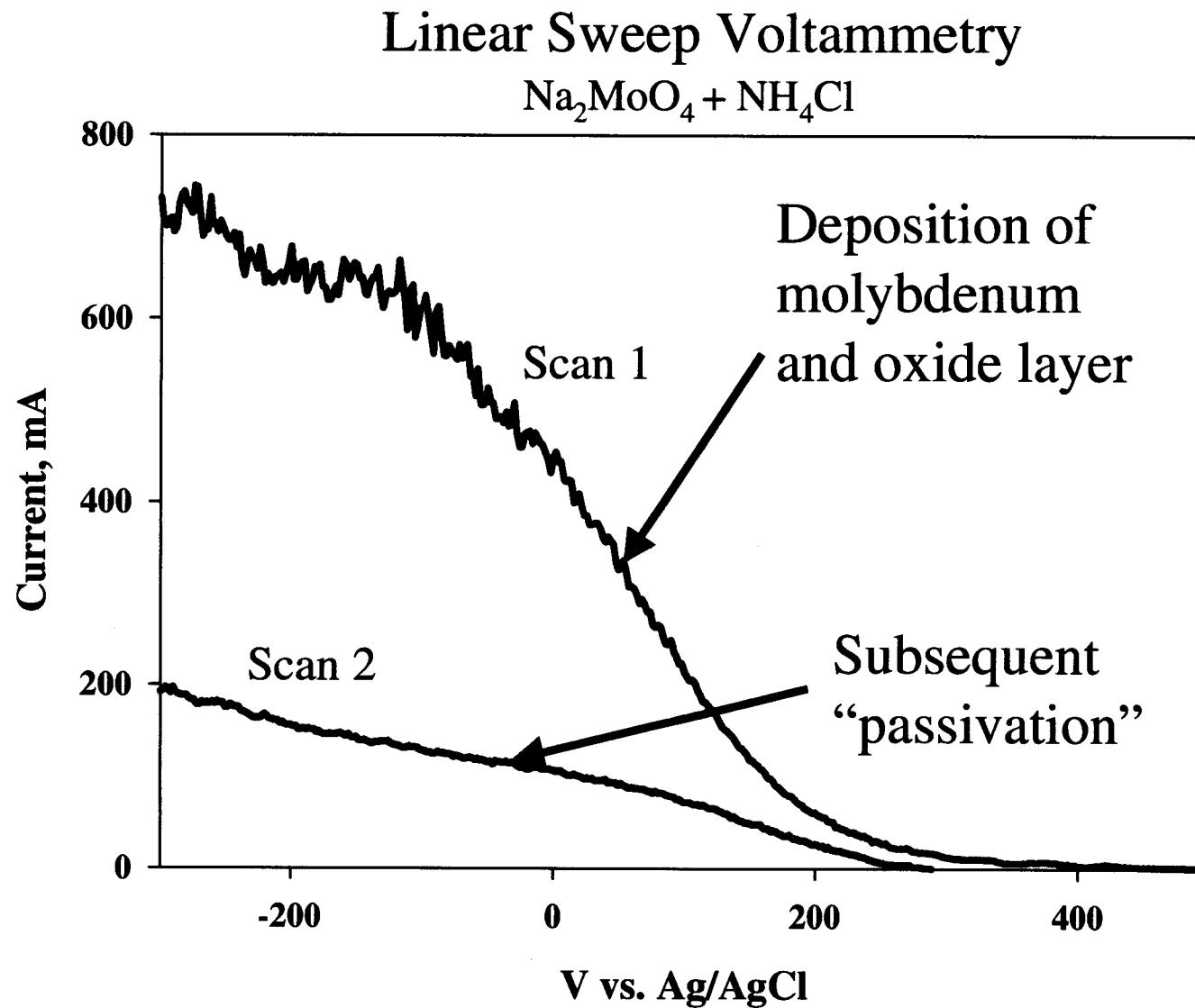


- Typical Permalloy baths operate at pH = 3.0
- Acidic baths favor molybdenum hydroxide formation
- Causes incorporation of oxides into the film
- Basic baths result in precipitation of iron hydroxides
- Optimal films deposited at pH of about 5.0



Electrodeposition of Mo at pH = 3.00

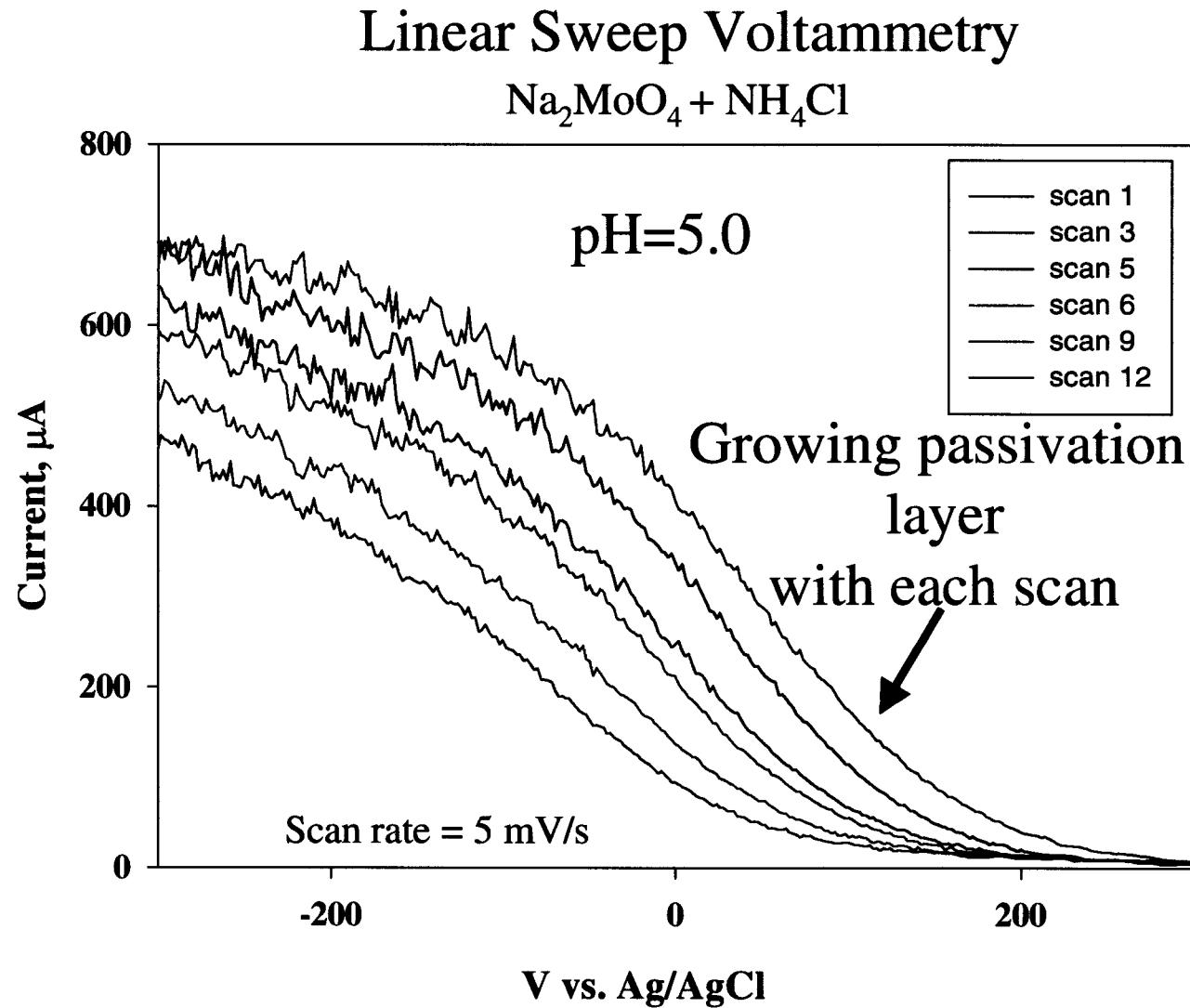
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Electrodeposition of Mo at pH = 5.00

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Conclusion



Ni-Fe-Mo

- Periodic application of reverse or anodic current (Pulse plating)
- Boric acid buffers to reduce surface pH
- Use another metal (i.e., Cr vs. Mo)

Combine with other energy storage elements

- High dielectric anodized Ta_2O_5 capacitors
- Solid state, thin film lithium ion microbatteries
- *Build up entire power circuits on silicon*



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